

Abstract of the Disclosure:

In order to calibrate a test system for semiconductor components, use is made of a test substrate which has connecting contact points that are associated with one another in pairs. The contact points of the pairs are disposed at different distances from one another and they are connected by conductor tracks of approximately the same length. As a result, equalization of all the signal paths is achieved. In each case, a probe belonging to a probe card or a reference probe is placed onto the connecting contact points of a pair, so that the test system can be calibrated as far as a respective connecting contact of a component.